

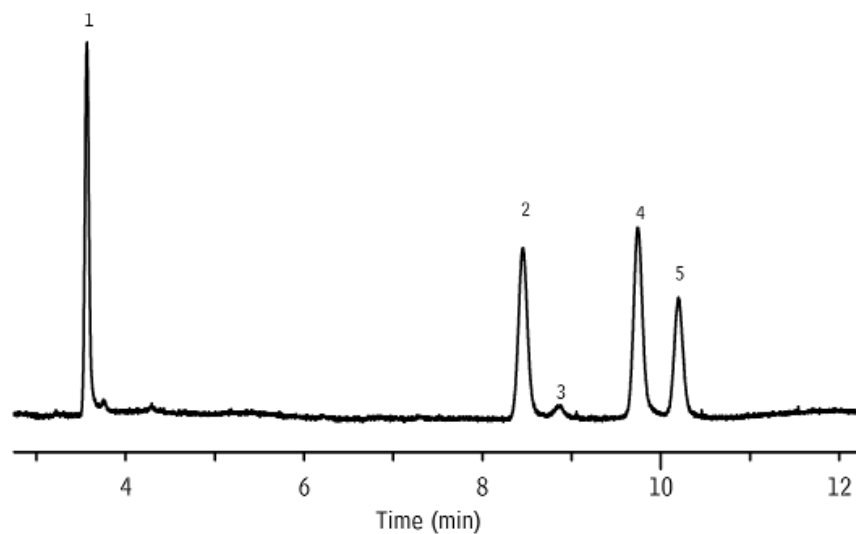
Residual Solvents Class 1 Rtx®-624

Column: Rtx®-624, 30m, 0.32mm ID, 1.8 μ m (cat.# 10970)
Sample: USP <467> Class 1 standard solution
(cat.# 36279) in 20mL headspace vial
Inj.: headspace injection (split ratio 1:5), 1mm split
liner, Siltek® deactivated (cat.# 20972-214.1)
Inj. temp.: 140°C
Carrier gas: helium, constant flow
Flow rate: 2.16mL/min., 35.3cm/sec.
Oven temp.: 40°C for 20 min. to 240°C @
10°C/min. (hold for 20 min.)
Det.: FID @ 240°C

Headspace Conditions

Instrument: Tekmar HT3
Transfer line temp.: 105°C
Valve oven temp.: 105°C
Sample temp.: 80°C
Sample equil. time: 45 min.
Vial pressure: 10psi
Pressurize time: 0.5 min.
Loop fill pressure: 5psi
Loop fill time: 2.00 min.
Inject time: 1.00 min.

1. 1,1-dichloroethene
2. 1,1,1-trichloroethane
3. carbon tetrachloride
4. benzene
5. 1,2-dichloroethane



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